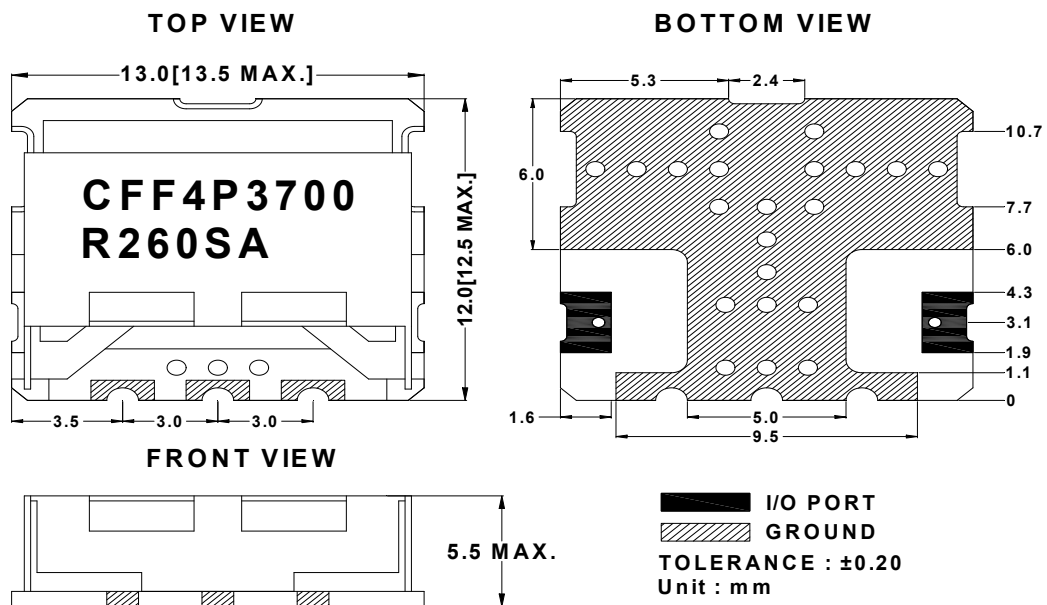


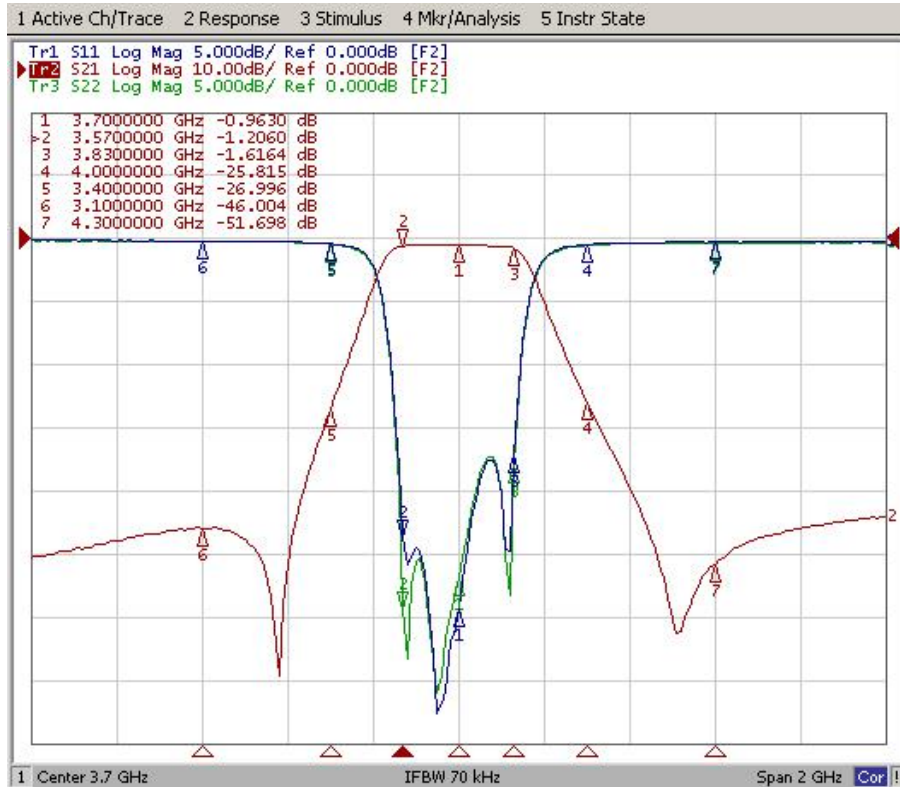
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	3700.0	MHz
Bandwidth [BW]	$f_0 \pm 130$ [3570~3830]	MHz
Insertion Loss in BW	1.8	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	25dB min. @ 4000	MHz
	25dB min. @ 3400	MHz
	35dB min. @ 3100	MHz
	35dB min. @ 4300	MHz
Group Delay Variation		ns max
Input Power	2	W max.
In/Out Impedance	50 $\Omega$	
Operation Temperature Range	-40°C to +85°C	

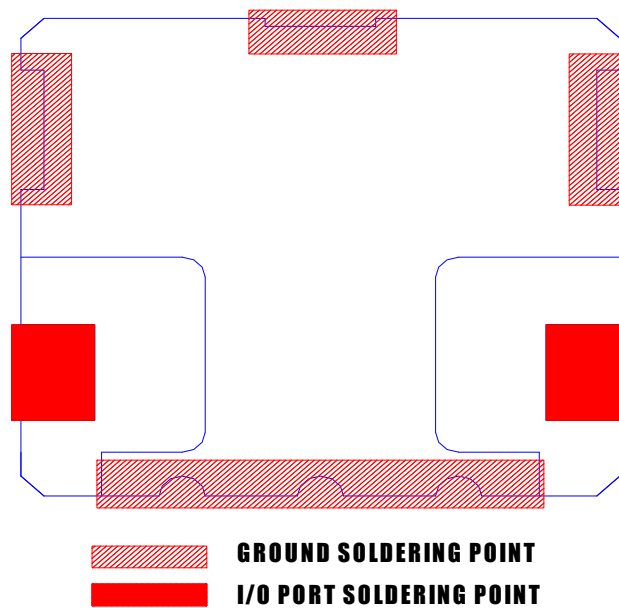
Mechanical Specification



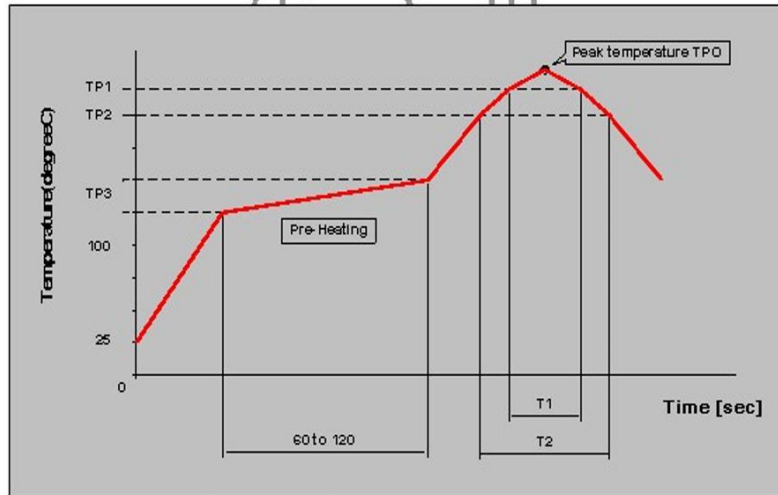
Plot Data



Recommended PC Board Pattern



**Soldering Condition**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180